

## **Current Report No. 15/2014**

*(Friday, 18 July 2014)*

*Legal basis: Art. 56.1.2 of the Polish Public Offering Act – current and periodical information*

### **Conclusion of a major agreement – bond issue agreement**

The Management Board of AB S.A. with its registered office in Wrocław (Issuer), pursuant to Section 5.1.3 of the Regulation of the Minister of Finance of 19 February 2009 on current and periodical information disclosed by issuers of securities (Journal of Laws of 2014, item 133), informs that on 18 July 2014 the Issuer concluded a bond issue agreement “AB S.A. Bond Issue Program for the total amount of PLN 100,000,000” (Agreement) with Bank Polska Kasa Opieki S.A. with its registered office in Warsaw (Bank).

Pursuant to the Agreement, the Issuer launched the AB S.A. Bond Issue Program (Program).

The key assumptions underlying the Program include:

1. The Program provides for several bond issues up to the total Program amount of PLN 100,000,000 (PLN one hundred million).
2. Dematerialised, unsecured bearer bonds will be issued under the Program by way of private placement, in compliance with Art. 9.3 of the Act of 29 June 1995 on bonds (Journal of laws of 2014, item 730).
3. Under the Program, the Issuer may issue coupon bonds with minimum maturities of 1 (one) year on which interest will accrue in compliance with terms and conditions of each series.
4. The Issuer may apply to have its bonds admitted to trading in the alternative trading system operated by BondSpot S.A. and/or on the Catalyst Market of the Warsaw Stock Exchange.

In accordance with the Agreement, the Bank will perform agreed operations relating to the arrangement of the issue, offering, registering and settlement of the bonds.

The criterion used to determine whether an agreement is material is its total value which must exceed the equivalent of 10% of the Issuer's equity.